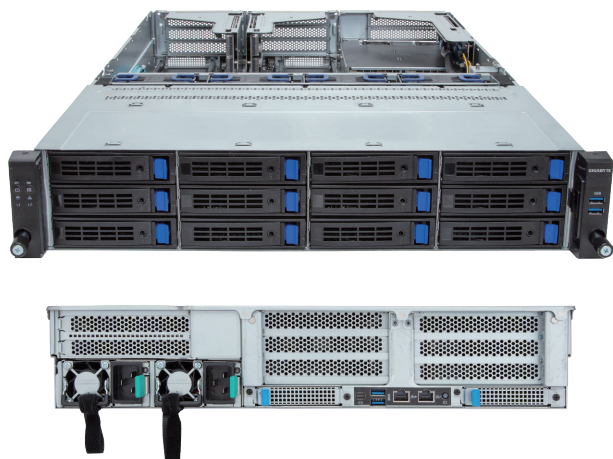


# R263-S33-AAF1

Rack Server - 2U UP 3 x PCIe Gen5 GPUs

intel  
XEON



## Features

- Supports up to 3 x Dual slot Gen5 GPU
- Single 5th/4th Gen Intel® Xeon® Scalable Processors
- Single Intel® Xeon® CPU Max Series
- 8-Channel DDR5 RDIMM, 16 x DIMMs
- Dual ROM Architecture supported
- 1 x 1Gb/s LAN port via Intel® I210-AT
- 12 x 3.5"/2.5" SATA/SAS hot-swappable bays
- 1 x M.2 slot with PCIe Gen3 x4 interface
- 3 x FHFL PCIe Gen5 x16 slots for GPUs
- 2 x OCP 3.0 Gen5 x16 slots
- 1+1 2400W 80 PLUS Platinum redundant power supplies

## Application

AI, AI Inference, Visual Computing, Networking, Hybrid/Private Cloud

## Specification

<b>Dimensions</b>	2U (W438 x H87.5 x D710 mm)	<b>TPM</b>	1 x TPM header with SPI interface (Optional TPM2.0 kit: CTM010)
<b>Motherboard</b>	MS33-DC0	<b>Power Supply</b>	1+1 2400W 80 PLUS Platinum redundant power supplies AC Input: 100-240V *The system power supply requires C19 power cord.
<b>CPU</b>	5th Generation Intel® Xeon® Scalable Processors 4th Generation Intel® Xeon® Scalable Processors Intel® Xeon® CPU Max Series Single processor, TDP up to 350W	<b>System Management</b>	ASPEED® AST2600 management controller GIGABYTE Management Console (AMI MegaRAC SP-X)
<b>Socket</b>	1 x LGA 4677 (Socket E)	<b>OS Compatibility</b>	Windows Server 2019 / 2022 RHEL 8.6 / 8.7 / 8.8 / 8.9 / 8.10 / 9.0 / 9.1 / 9.2 / 9.3 / 9.4 SLES 15 SP4 / SP5 / SP6 Ubuntu 22.04 / 22.04.1 / 22.04.2 / 22.04.3 / 22.04.4 / 24.04 LTS VMware ESXi 7.0 Update 3o / 8.0 Update 1, Update 2, Update 3 Citrix Hypervisor 8.2 LTSR CU1
<b>Chipset</b>	Intel® C741 Chipset	<b>System Fans</b>	4 x 80x80x38mm (18,300rpm)
<b>Memory</b>	16 x DIMM slots, 8-Channel DDR5 memory RDIMM up to 96GB; 3DS RDIMM up to 256GB Memory speed: Up to 5600 MT/s (1DPC), 4400 MT/s (2DPC)	<b>Operating Properties</b>	Operating temperature: 10°C to 35°C Operating humidity: 8-80% (non-condensing) Non-operating temperature: -40°C to 60°C Non-operating humidity: 20%-95% (non-condensing)
<b>LAN</b>	1 x 1Gb/s LAN port (1 x Intel® I210-AT) - Supports NCSI function 1 x 10/100/1000 Mbps Management LAN	<b>Packaging Content</b>	1 x R263-S33-AAF1, 1 x CPU heatsink, 3 x Carrier clips, 1 x Mini-DP to D-Sub cable, 1 x 2-Section Rail kit, 3 x GPU power cables (2x PCIe 8pin) Packaging Dimensions: 989 x 594 x 279 mm
<b>Video</b>	ASPEED® AST2600 Integrated 2D Graphic Adapter	<b>Part Numbers</b>	Barebone package (5th/4th Gen): 6NR263S33DR000ABF1* Barebone package (4th Gen): 6NR263S33DR000AAF1* - 2-Section Rail kit (CMA not supported): 25HB2-3A0203-K0R - CPU heatsink: 25ST1-4Z3200-S7R - Mini-DP to D-Sub cable: 25CRN-200801-K1R - Power supply: 25EP0-224000-D0S - C19 power cord 125V/15A (US): 25CP1-018000-Q0R (Optional) - C19 power cord 250V/16A (EU): 25CP3-01830H-Q0R (Optional) - C19 power cord 125V/15A (JP): 25CPA-01830B-Q0R (Optional)
<b>Storage</b>	12 x 3.5"/2.5" SATA/SAS hot-swappable bays *SAS card is required for SAS devices support 1 x M.2 slot (M-key, PCIe Gen3 x4, supports 2280/22110 cards)		
<b>RAID</b>	Intel® SATA RAID 0/1/10/5		
<b>Expansion Slots</b>	3 x FHFL PCIe Gen5 x16 slots for GPUs 2 x OCP 3.0 Gen5 x16 slots - Supporte NCSI function		
<b>Backplane Board</b>	Speed and bandwidth: PCIe Gen4 x4 or SATA 6Gb/s or SAS 12Gb/s		
<b>I/O Ports</b>	Front: 2 x USB 3.2 Gen1 Rear: 2 x USB 3.2 Gen1, 1 x Mini-DP, 1 x RJ45, 1 x MLAN Internal: 1 x TPM header, 1 x VROC connector		



Learn more at <https://www.GIGABYTE.com/enterprise>

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